

ABSTRACT OF THE DISCLOSURE

A contact angle for a liquid on a substrate is set by a surface treatment process such that defects do not occur in a thin film pattern. In particular, the contact angle is set in a range of 15° to 45° . By doing this, it is possible to provide a device, a conductive thin film wiring device, and a method for forming a thin film pattern in which defects such as disconnections and short circuits can be prevented in a thin film pattern which is formed by an ink jet method.